



32692  
Customer Number

Patent  
Case No.: 53434US009

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

First Named Inventor: HOGERTON, PETER B.  
Application No.: 09/690,600      Group Art Unit: 2827  
Filed: October 17, 2000      Examiner: Luan C. Thai  
Title: SOLVENT ASSISTED BURNISHING OF PRE-UNDERFILLED  
SOLDER-BUMPED WAFERS FOR FLIPCHIP BONDING

**NOTICE OF APPEAL PURSUANT TO 37 CFR § 1.191**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**CERTIFICATE OF MAILING**  
I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:

**JUL 23 2004**

Date

*Kathleen M. Murray*  
Signed by: Kathleen M. Murray

Dear Sir:

An appeal is made to the Board of Patent Appeals and Interferences from the last decision of the Examiner rejecting claims 16-19.

A Request for Extension of Time Under 37 CFR § 1.136(a) is enclosed.

Please charge the fee provided in 37 CFR § 1.17(b), and if necessary, charge any additional fees, or credit any overpayment to Deposit Account No. 13-3723. One copy of this sheet marked duplicate is also enclosed.

Respectfully submitted,

*23 July 2004*  
Date

By: *Dean M. Harts*  
Dean M. Harts, Reg. No.: 47,634  
Telephone No.: (651) 737-2325

Office of Intellectual Property Counsel  
3M Innovative Properties Company  
Facsimile No.: 651-736-3833